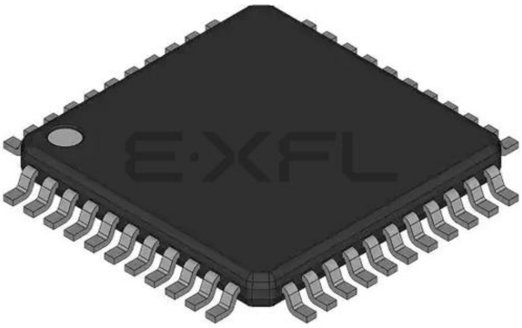


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

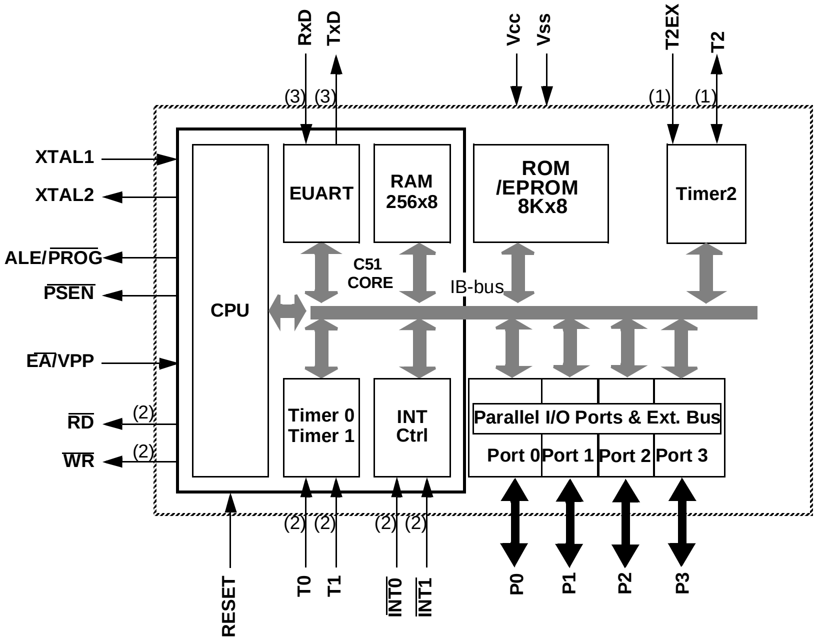
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-VQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at80c32x2-rlrum

Table 1. Memory Size

	ROM (bytes)	EPROM (bytes)	TOTAL RAM (bytes)
TS80C32X2	0	0	256
TS80C52X2	8k	0	256
TS87C52X2	0	8k	256

Block Diagram



Notes:
1. Alternate function of Port 1
2. Alternate function of Port 3

Dual Data Pointer Register (Ddptr)

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called
DPS = AUXR1/bit0 (See Table 5.) that allows the program code to switch between them (Refer to Figure 3).

Figure 3. Use of Dual Pointer

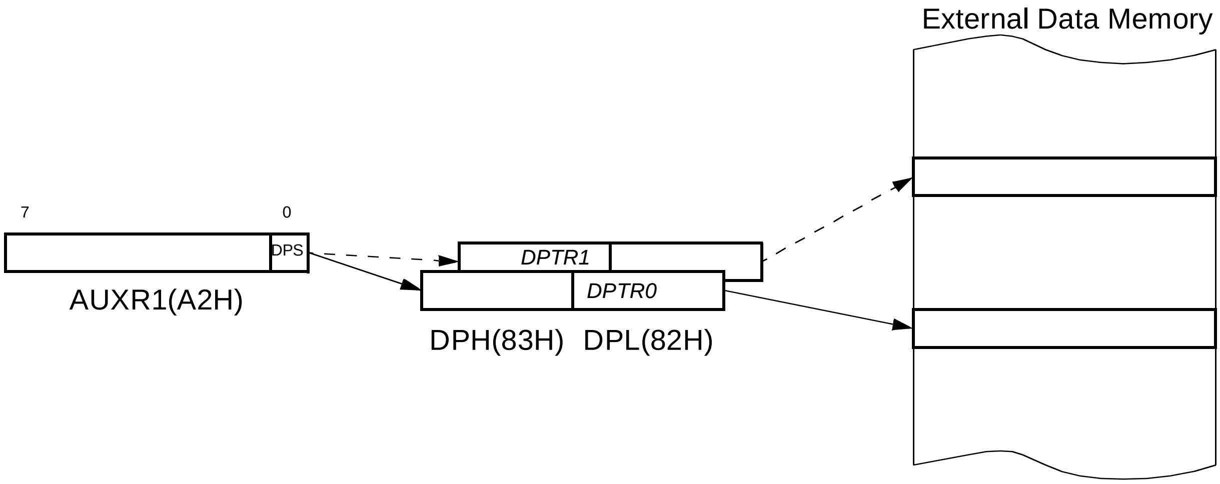


Table 4. AUXR1: Auxiliary Register 1

7	6	5	4	3	2	1	0
-	**-**	**-**	**-**	**GF3**	**0**	**-**	**DPS**

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
3	GF3	This bit is a general purpose user flag
2	0	**Reserved** Always stuck at 0
1	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
0	DPS	**Data Pointer Selection** Clear to select DPTR0. Set to select DPTR1.

Reset Value = XXXX XXX0
Not bit addressable

Application

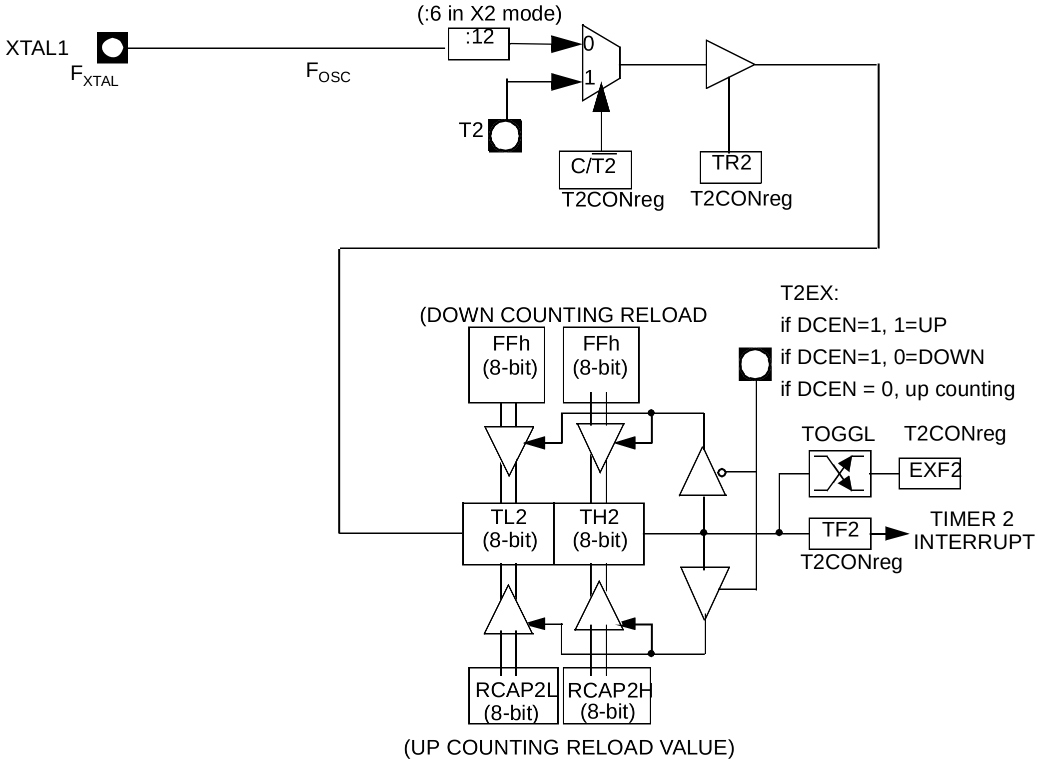
Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

ASSEMBLY LANGUAGE

```
; Block move using dual data pointers
; Destroys DPTR0, DPTR1, A and PSW
; note: DPS exits opposite of entry state
; unless an extra INC AUXR1 is added
;
00A2     AUXR1 EQU 0A2H
;
0000 909000MOV DPTR,#SOURCE ; address of SOURCE
0003 05A2 INC AUXR1 ; switch data pointers
0005 90A000 MOV DPTR,#DEST ; address of DEST
0008    LOOP:
0008 05A2 INC AUXR1 ; switch data pointers
000A E0 MOVX A,atDPTR ; get a byte from SOURCE
000B A3 INC DPTR ; increment SOURCE address
000C 05A2 INC AUXR1 ; switch data pointers
000E F0 MOVX atDPTR,A ; write the byte to DEST
000F A3 INC DPTR ; increment DEST address
0010 70F6JNZ LOOP ; check for 0 terminator
0012 05A2 INC AUXR1 ; (optional) restore DPS
```

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.

Figure 4. Auto-reload Mode Up/Down Counter (DCEN = 1)



Programmable Clock-output

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 5) . The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers :

$$Clock-OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz ($F_{OSC}/2^{16)}$ to 4 MHz ($F_{OSC}/4$). The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/$\overline{T2}$ bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.

Figure 5. Clock-Out Mode $C/\overline{T2} = 0$

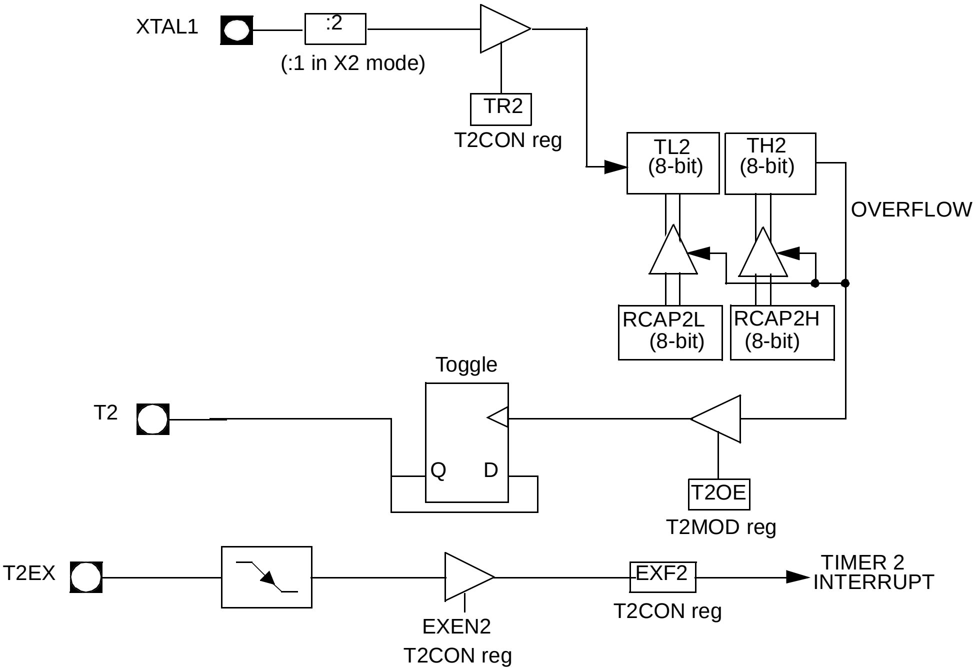


Table 6. T2MOD Register

T2MOD - Timer 2 Mode Control Register (C9h)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	T2OE	DCEN

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
3	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
2	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
1	T2OE	**Timer 2 Output Enable bit** Clear to program P1.0/T2 as clock input or I/O port. Set to program P1.0/T2 as clock output.
0	DCEN	**Down Counter Enable bit** Clear to disable timer 2 as up/down counter. Set to enable timer 2 as up/down counter.

Reset Value = XXXX XX00b

Not bit addressable

`1111 0000b`).

For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. `1111 0011b`).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. `1111 0001b`).

Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

```
    SADDR 0101 0110b
    SADEN 1111 1100b

  Broadcast =SADDR OR SADEN1111 111Xb
```

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:SADDR1111 0001b
    SADEN1111 1010b
    Broadcast1111 1X11b,

Slave B:SADDR1111 0011b
    SADEN1111 1001b
    Broadcast1111 1X11B,

Slave C:SADDR=1111 0010b
    SADEN1111 1101b
    Broadcast1111 1111b
```

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.

Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are `XXXX XXXXb` (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

Table 7. SADEN Register

SADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b

Not bit addressable

Table 8. SADDR Register

SADDR - Slave Address Register (A9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b

Not bit addressable

Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

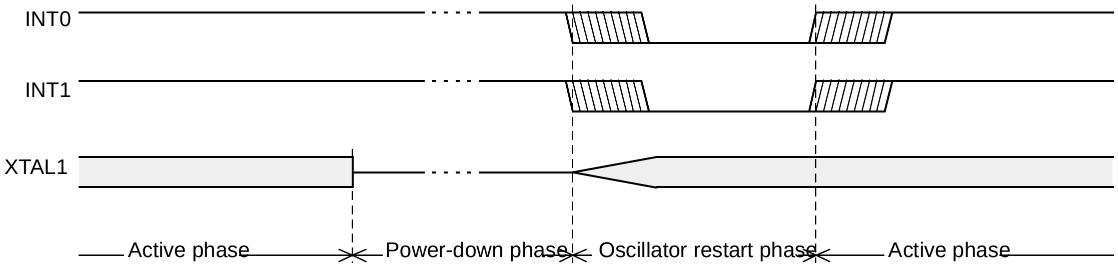
Power-down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 10., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.
Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 10. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.
Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C52X2 into power-down mode.

Figure 10. Power-down Exit Waveform



ONCE^{TM} Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C52X2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C52X2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and $\overline{\text{PSEN}}$ is high.
- Hold ALE low as RST is deactivated.

While the TS80C52X2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 16. External Pin Status during ONCE Mode

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull-up	Weak pull-up	Float	Weak pull-up	Weak pull-up	Weak pull-up	Active

TS80C52X2

ROM Structure

The TS80C52X2 ROM memory is divided in three different arrays:

- the code array:8 Kbytes.
- the encryption array:64 bytes.
- the signature array:4 bytes.

ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

Program Lock Bits

The lock bits when programmed according to Table 19. will provide different level of protection for the on-chip code and data.

Table 19. Program Lock bits

Program Lock Bits				
Security level	LB1	LB2	LB3	Protection Description
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset.

U: unprogrammed
P: programmed

Signature bytes

The TS80C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

Verify Algorithm

Refer to Section "Verify Algorithm".

Control and program signals must be held at the levels indicated in Table 35.

Definition of terms

Address Lines: P1.0-P1.7, P2.0-P2.4 respectively for A0-A12

Data Lines: P0.0-P0.7 for D0-D7

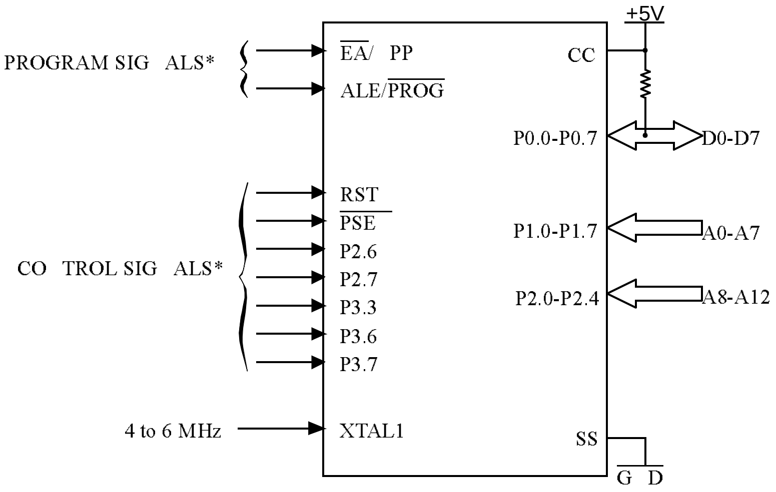
Control Signals: RST, $\overline{\text{PSEN}}$, P2.6, P2.7, P3.3, P3.6, P3.7.

Program Signals: ALE/$\overline{\text{PROG}}$, $\overline{\text{EA}}$/VPP.

Table 20. EPROM Set-up Modes

Mode	RST	PSEN	ALE/ $\overline{\text{PROG}}$	$\overline{\text{EA}}$/ VPP	P2.6	P2.7	P3.3	P3.6	P3.7
Program Code data	1	0	⊔	12.75V	0	1	1	1	1
Verify Code data	1	0	1	1	0	⊔	0	1	1
Program Encryption Array Address 0-3Fh	1	0	⊔	12.75V	0	1	1	0	1
Read Signature Bytes	1	0	1	1	0	⊔	0	0	0
Program Lock bit 1	1	0	⊔	12.75V	1	1	1	1	1
Program Lock bit 2	1	0	⊔	12.75V	1	1	1	0	0
Program Lock bit 3	1	0	⊔	12.75V	1	0	1	1	0

Figure 11. Set-Up Modes Configuration



* See Table 31. for proper value on these inputs

Electrical Characteristics

Absolute Maximum Ratings(1)

Ambiant Temperature Under Bias:

C = commercial	0°C to 70°C
I = industrial	-40°C to 85°C
Storage Temperature	-65°C to + 150°C
Voltage on V_{CC} to V_{SS}	-0.5V to + 7 V
Voltage on V_{PP} to V_{SS}	-0.5V to + 13 V
Voltage on Any Pin to V_{SS}	-0.5V to V_{CC} + 0.5V
Power Dissipation	1 W(2)

Notes:
1. Stresses at or above those listed under “ Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That’s why, while keeping measurements under Reset, Atmel presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

```
Label:                SJMP Label (80 FE)
```

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.

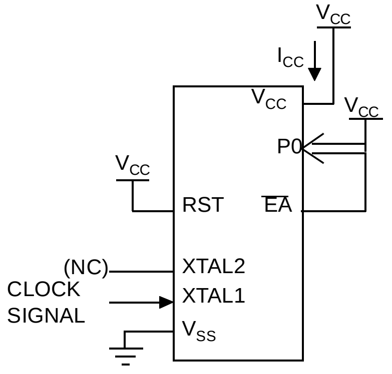
Table 22. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 (6)			0.3 0.45 1.0	V V V	I_{OL} = 100 μA(4) I_{OL} = 1.6 mA(4) I_{OL} = 3.5 mA(4)
V_{OL1}	Output Low Voltage, port 0 (6)			0.3 0.45 1.0	V V V	I_{OL} = 200 μA(4) I_{OL} = 3.2 mA(4) I_{OL} = 7.0 mA(4)
V_{OL2}	Output Low Voltage, ALE, $\overline{\text{PSEN}}$			0.3 0.45 1.0	V V V	I_{OL} = 100 μA(4) I_{OL} = 1.6 mA(4) I_{OL} = 3.5 mA(4)

Port 0: 26 mA
Ports 1, 2 and 3: 15 mA
Maximum total I_{OL} for all output pins: 71 mA
If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

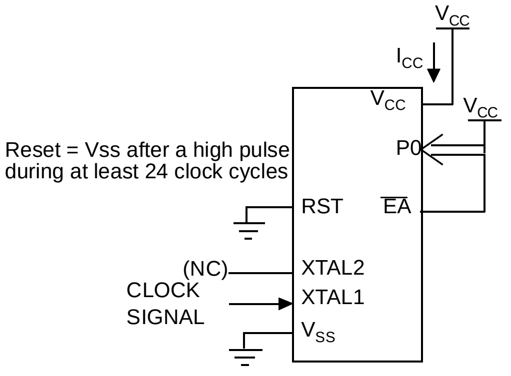
7. For other values, please contact your sales office.
8. Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 17.), V_{IL} = V_{SS} + 0.5V,
V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; $\overline{EA}$ = Port 0 = V_{CC}; RST = V_{SS}. The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.

Figure 13. I_{CC} Test Condition, under reset



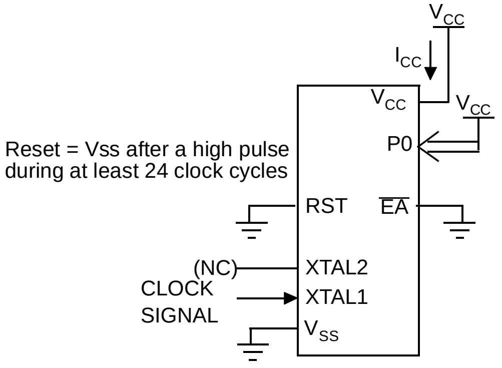
All other pins are disconnected.

Figure 14. Operating I_{CC} Test Condition



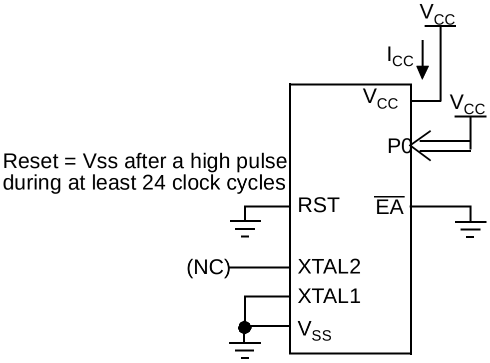
All other pins are disconnected.

Figure 15. I_{CC} Test Condition, Idle Mode



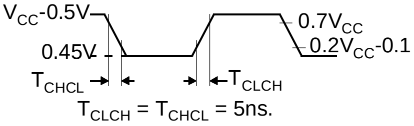
All other pins are disconnected.

Figure 16. I_{CC} Test Condition, Power-down Mode



All other pins are disconnected.

Figure 17. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes



AC Parameters

Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a "T" (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example:T_{AVLL} = Time for Address Valid to ALE Low.
T_{LLPL} = Time for ALE Low to $\overline{PSEN}$ Low.

T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; V_{CC} = 5V ± 10%; -M and -V ranges.
T_A = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; V_{CC} = 5V ± 10%; -M and -V ranges.
T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; 2.7 V < $V_{CC} <$ 5.5V; -L range.
T_A = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; 2.7 V < $V_{CC} <$ 5.5V; -L range.

Table 24. gives the maximum applicable load capacitance for Port 0, Port 1, 2 and 3, and ALE and $\overline{PSEN}$ signals. Timings will be guaranteed if these capacitances are respected. Higher capacitance values can be used, but timings will then be degraded.

Table 24. Load Capacitance versus speed range, in pF

	-M	-V	-L
Port 0	100	50	100
Port 1, 2, 3	80	50	80
ALE / $\overline{PSEN}$	100	30	100

Table 5., Table 29. and Table 32. give the description of each AC symbols.

Table 27., Table 30. and Table 33. give for each range the AC parameter.

Table 27. AC Parameters for Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T	25		33		25		50		33		ns
T_{LHLL}	40		25		42		35		52		ns
T_{AVLL}	10		4		12		5		13		ns
T_{LLAX}	10		4		12		5		13		ns
T_{LLIV}		70		45		78		65		98	ns
T_{LLPL}	15		9		17		10		18		ns
T_{PLPH}	55		35		60		50		75		ns
T_{PLIV}		35		25		50		30		55	ns
T_{PXIX}	0		0		0		0		0		ns
T_{PXIZ}		18		12		20		10		18	ns
T_{AVIV}		85		53		95		80		122	ns
T_{PLAZ}		10		10		10		10		10	ns

Table 28. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{LHLL}	Min	2 T - x	T - x	10	8	15	ns
T_{AVLL}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLAX}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLIV}	Max	4 T - x	2 T - x	30	22	35	ns
T_{LLPL}	Min	T - x	0.5 T - x	10	8	15	ns
T_{PLPH}	Min	3 T - x	1.5 T - x	20	15	25	ns
T_{PLIV}	Max	3 T - x	1.5 T - x	40	25	45	ns
T_{PXIX}	Min	x	x	0	0	0	ns
T_{PXIZ}	Max	T - x	0.5 T - x	7	5	15	ns
T_{AVIV}	Max	5 T - x	2.5 T - x	40	30	45	ns
T_{PLAZ}	Max	x	x	10	10	10	ns

Table 30. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDX}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T_{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T_{AVWL}	75		47		80		70		103		ns
T_{QVWX}	10		7		15		5		13		ns
T_{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

Table 31. AC Parameters for a Variable Clock: Derating Formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{RLRH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{WLWH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{RLDV}	Max	5 T - x	2.5 T - x	25	23	30	ns
T_{RHDX}	Min	x	x	0	0	0	ns
T_{RHDZ}	Max	2 T - x	T - x	20	15	25	ns
T_{LLDV}	Max	8 T - x	4T -x	40	35	45	ns
T_{AVDV}	Max	9 T - x	4.5 T - x	60	50	65	ns
T_{LLWL}	Min	3 T - x	1.5 T - x	25	20	30	ns
T_{LLWL}	Max	3 T + x	1.5 T + x	25	20	30	ns
T_{AVWL}	Min	4 T - x	2 T - x	25	20	30	ns
T_{QVWX}	Min	T - x	0.5 T - x	15	10	20	ns
T_{QVWH}	Min	7 T - x	3.5 T - x	15	10	20	ns
T_{WHQX}	Min	T - x	0.5 T - x	10	8	15	ns
T_{RLAZ}	Max	x	x	0	0	0	ns
T_{WHLH}	Min	T - x	0.5 T - x	15	10	20	ns
T_{WHLH}	Max	T + x	0.5 T + x	15	10	20	ns

External Data Memory Write Cycle

Figure 19. External Data Memory Write Cycle

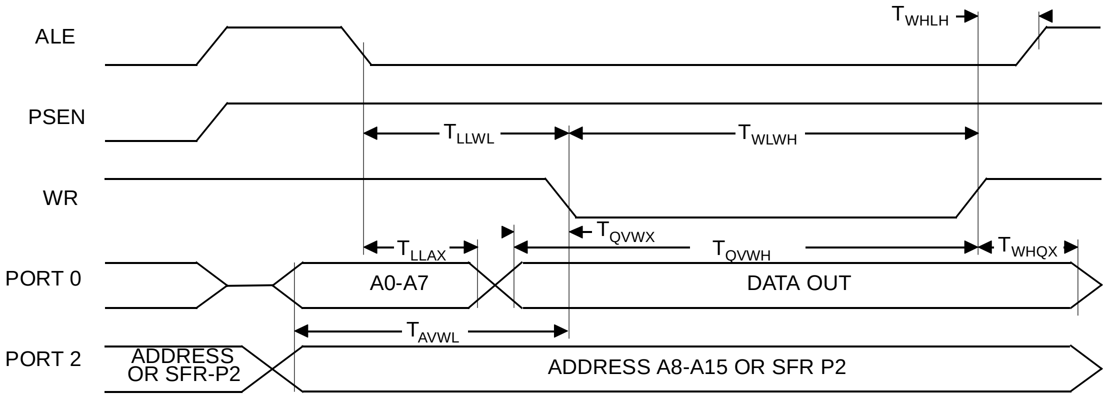
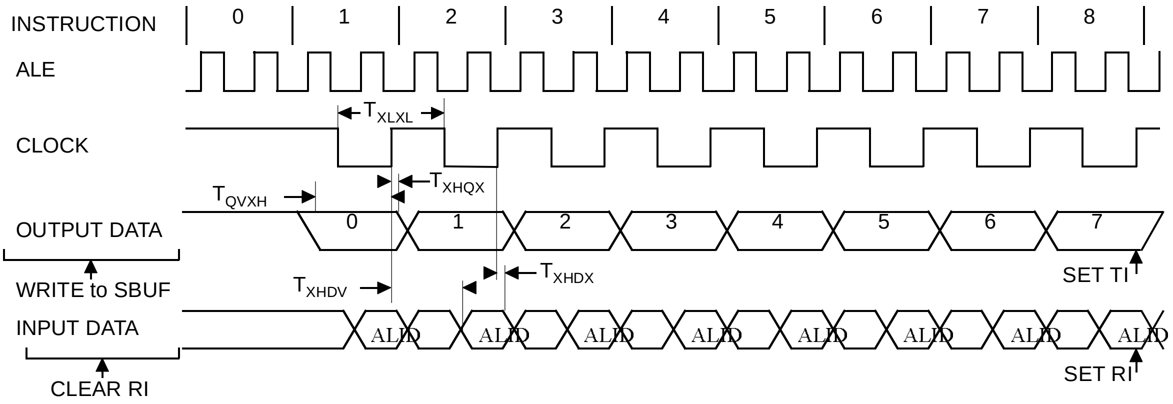


Table 34. AC Parameters for a Variable Clock: Derating Formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{XLXL}	Min	12 T	6 T				ns
T_{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T_{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T_{XHDX}	Min	x	x	0	0	0	ns
T_{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

Shift Register Timing Waveforms

Figure 21. Shift Register Timing Waveforms



Ordering Information

Table 37. Possible Ordering Entries

Part Number(3)	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS80C32X2-MCA	ROMLess	5V ±10%	Commercial	40 MHz(1)	PDIL40	Stick
TS80C32X2-MCB	ROMLess	5V ±10%	Commercial	40 MHz(1)	PLCC44	Stick
TS80C32X2-MCC	ROMLess	5V ±10%	Commercial	40 MHz(1)	PQFP44	Tray
TS80C32X2-MCE	ROMLess	5V ±10%	Commercial	40 MHz(1)	VQFP44	Tray
TS80C32X2-LCA	ROMLess	2.7 to 5.5V	Commercial	30 MHz(1)	PDIL40	Stick
TS80C32X2-LCB	ROMLess	2.7 to 5.5V	Commercial	30 MHz(1)	PLCC44	Stick
TS80C32X2-LCC	ROMLess	2.7 to 5.5V	Commercial	30 MHz(1)	PQFP44	Tray
TS80C32X2-LCE	ROMLess	2.7 to 5.5V	Commercial	30 MHz(1)	VQFP44	Tray
TS80C32X2-VCA	ROMLess	5V ±10%	Commercial	60 MHz(3)	PDIL40	Stick
TS80C32X2-VCB	ROMLess	5V ±10%	Commercial	60 MHz(3)	PLCC44	Stick
TS80C32X2-VCC	ROMLess	5V ±10%	Commercial	60 MHz(3)	PQFP44	Tray
TS80C32X2-VCE	ROMLess	5V ±10%	Commercial	60 MHz(3)	VQFP44	Tray
TS80C32X2-MIA	ROMLess	5V ±10%	Industrial	40 MHz(1)	PDIL40	Stick
TS80C32X2-MIB	ROMLess	5V ±10%	Industrial	40 MHz(1)	PLCC44	Stick
TS80C32X2-MIC	ROMLess	5V ±10%	Industrial	40 MHz(1)	PQFP44	Tray
TS80C32X2-MIE	ROMLess	5V ±10%	Industrial	40 MHz(1)	VQFP44	Tray
TS80C32X2-LIA	ROMLess	2.7 to 5.5V	Industrial	30 MHz(1)	PDIL40	Stick
TS80C32X2-LIB	ROMLess	2.7 to 5.5V	Industrial	30 MHz(1)	PLCC44	Stick
TS80C32X2-LIC	ROMLess	2.7 to 5.5V	Industrial	30 MHz(1)	PQFP44	Tray
TS80C32X2-LIE	ROMLess	2.7 to 5.5V	Industrial	30 MHz(1)	VQFP44	Tray
TS80C32X2-VIA	ROMLess	5V ±10%	Industrial	60 MHz(3)	PDIL40	Stick
TS80C32X2-VIB	ROMLess	5V ±10%	Industrial	60 MHz(3)	PLCC44	Stick
TS80C32X2-VIC	ROMLess	5V ±10%	Industrial	60 MHz(3)	PQFP44	Tray
TS80C32X2-VIE	ROMLess	5V ±10%	Industrial	60 MHz(3)	VQFP44	Tray
AT80C32X2-3CSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz(1)	PDIL40	Stick
AT80C32X2-SLSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz(1)	PLCC44	Stick
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz(1)	VQFP44	Tray
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz(1)	VQFP44	Tape & Reel
AT80C32X2-3CSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz(1)	PDIL40	Stick
AT80C32X2-SLSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz(1)	PLCC44	Stick

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